



Docket No. 55058 (70820)

#11/A  
2/19/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Y. Chikama, et al.

U.S.S.N.: 09/648,657

ART UNIT: 1746

FILED: August 25, 2000

EXAMINER: A. K. Alanko

FOR: METHOD FOR FABRICATING METAL WIRINGS

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CERTIFICATE OF MAILING

I hereby certify that this Letter (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service as first class mail, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on February 4, 2003.

  
Maggie C. Hamelin

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Assistant Commissioner for Patents  
WASHINGTON, D.C. 20231

AMENDMENT

The following amendment is in response to the Office Action mailed October 4, 2002, in the above referenced application. Kindly amend the application as follows:

IN THE CLAIMS

Please cancel claims 3 and 10 without prejudice or disclaimer.

Kindly amend claim 1, as follows:

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- A1 Sub B1
1. (amended) A method for fabricating metal wirings, comprising the steps of:  
forming a ground resin film by applying a resin onto an insulating substrate;  
patterning the ground resin film; and  
forming a low-resistance metal film selectively on and over the patterned ground resin film by a wet film formation technique, wherein the low-resistance metal film is a single layer